



4 Pad Ceramic Package Quartz Crystal, 1.0 mm x 1.2 mm



ILCX21 Series

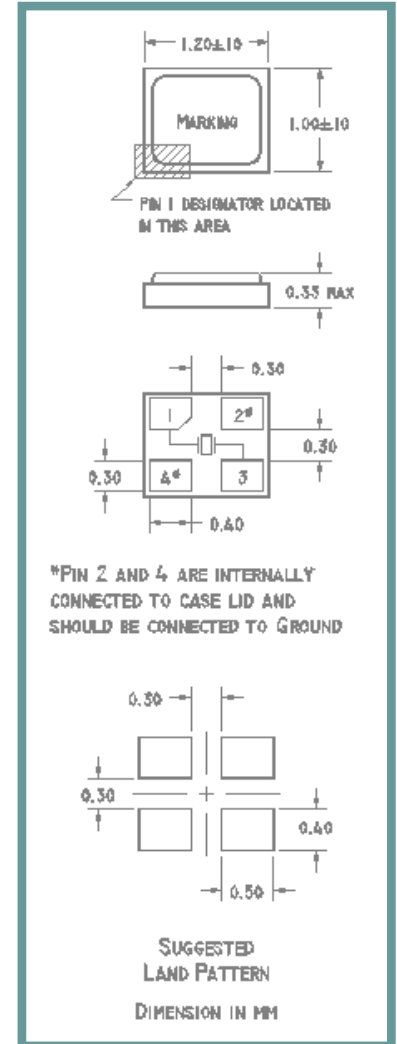
Product Features:

- Low Cost SMD Package
- Ultra Miniature Package
- Compatible with Leadfree Processing

Applications:

- Fibre Channel
- Server & Storage
- Sonet /SDH
- 802.11 / Wifi
- T1/E1, T3/E3
- IOT

Frequency	36 MHz to 80 MHz (Contact Sales Representative for developed frequencies)
ESR (Equivalent Series Resistance)	
36.0 MHz – 40.0 MHz	150 Ω Max.
40.0 MHz – 48.0 MHz	80 Ω Max.
48.0 MHz – 80.0 MHz	60 Ω Max.
Shunt Capacitance (C0)	3.0 pF Max.
Frequency Tolerance @ 25° C	± 30 ppm Standard (see Part Number Guide for more options)
Frequency Stability over Temperature	± 50 ppm Standard (see Part Number Guide for more options)
Crystal Cut	AT Cut
Load Capacitance	6 pF Standard
Drive Level	100 μ W Max.
Aging	± 3 ppm Max. / Year Standard
Temperature	
Operating	-20° C to +70° C (see Part Number Guide for more options)
Storage	-40° C to +85° C



Part Number Guide		Sample Part Number: ILCX21 - FB1F6 - 37.400				
Package	Tolerance (ppm) at Room Temperature	Stability (ppm) over Operating Temperature	Operating Temperature Range	Mode (overtone)	Load Capacitance (pF)	Frequency
ILCX21 -	B = ± 50 ppm	B = ± 50 ppm	0 = 0° C to +50° C	F = Fundamental	6 pF Standard Or Specify	- 37.400 MHz
	F = ± 30 ppm	F = ± 30 ppm**	1 = 0° C to +70° C			
	G = ± 25 ppm	G = ± 25 ppm**	2 = -10° C to +60° C			
	H = ± 20 ppm	H = ± 20 ppm**	3 = -20° C to +70° C			
	I = ± 15 ppm	I = ± 15 ppm**	5 = -40° C to +85° C			
J = ± 10 ppm*	J = ± 10 ppm**	9 = -10° C to +50° C				

* Not available at all frequencies. ** Not available for all temperature ranges.



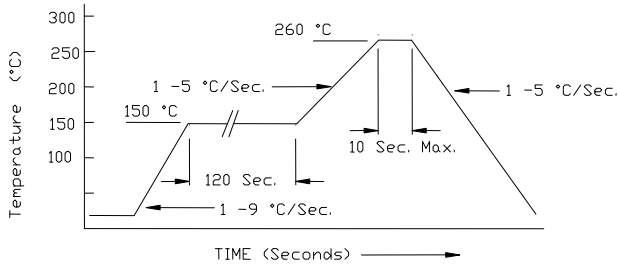
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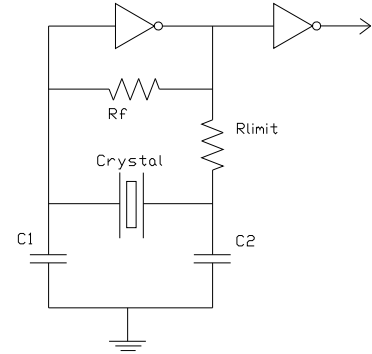
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Pb Free Solder Reflow Profile:

Typical Circuit:



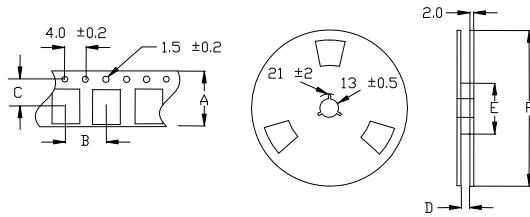
*Units are backward compatible with 240C reflow processes



Package Information:

MSL = 1
Termination = e4 (Au over Ni over W base metal).

Tape and Reel Information:



Quantity per Reel	5000
A	8 +/- .3
B	4 +/- .2
C	3.5 +/- .2
D	9 +/- .1 or 12 +/- .3
E	60 / 80
F	180

Environmental Specifications

Thermal Shock	MIL-STD-883, Method 1011, Condition A
Moisture Resistance	MIL-STD-883, Method 1004
Mechanical Shock	MIL-STD-883, Method 2002, Condition B
Mechanical Vibration	MIL-STD-883, Method 2007, Condition A
Resistance to Soldering Heat	J-STD-020C, Table 5-2 Pb-free devices (except 2 cycles max)
Hazardous Substance	Pb-Free / RoHS / Green Compliant
Solderability	JESD22-B102-D Method 2 (Preconditioning E)
Terminal Strength	MIL-STD-883, Method 2004, Test Condition D
Gross Leak	MIL-STD-883, Method 1014, Condition C
Fine Leak	MIL-STD-883, Method 1014, Condition A2, R1=2x10 ⁻⁸ atm cc/s
Solvent Resistance	MIL-STD-202, Method 215

Marking

Line 1: I, Date Code (yww)